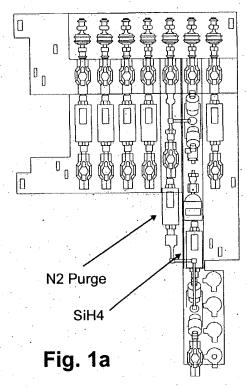
Atty Dkt. No.: AMAT/5335C1
U.S. Serial No.: Unknown Conf. No.: Unknown
Filed: July 22, 2003
Title: CVD TISIN BARRIER FOR COPPER INTEGRATION
Inventor: Chen et al.
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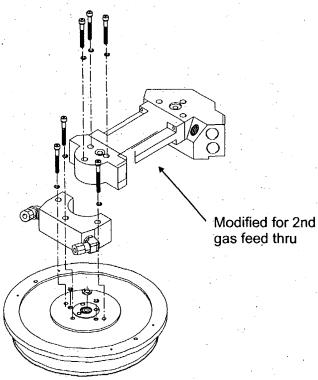


Fig. 1b

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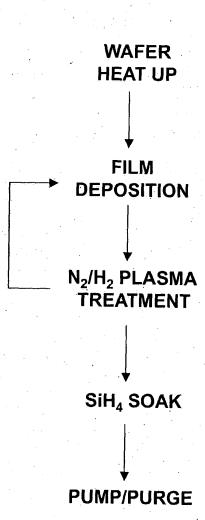


Fig. 2

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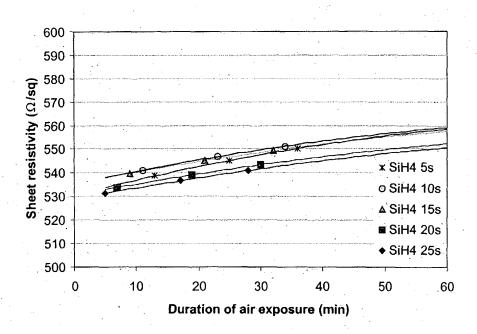


Fig. 3A

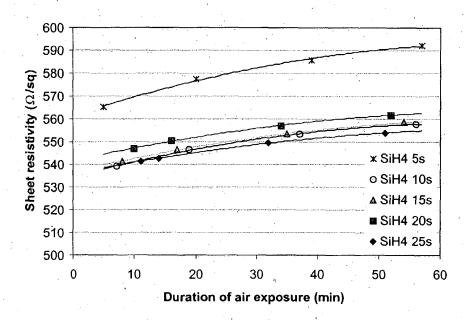
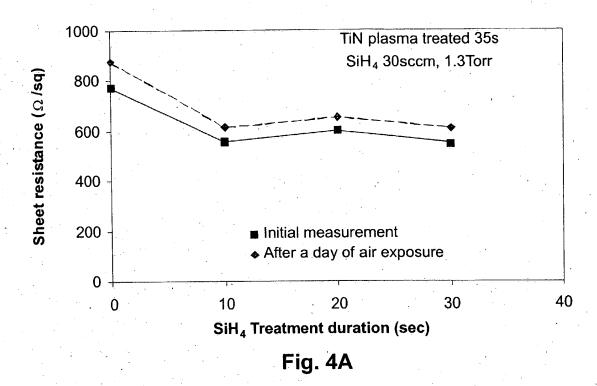


Fig. 3B

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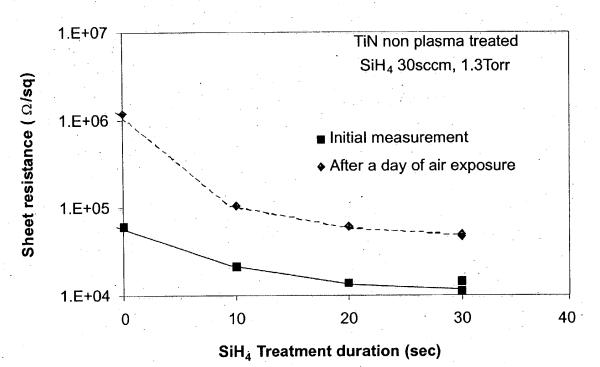


Fig. 4B

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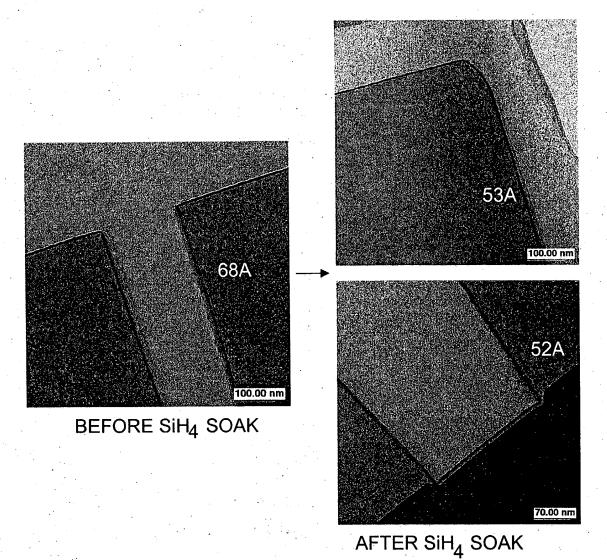


Fig. 5

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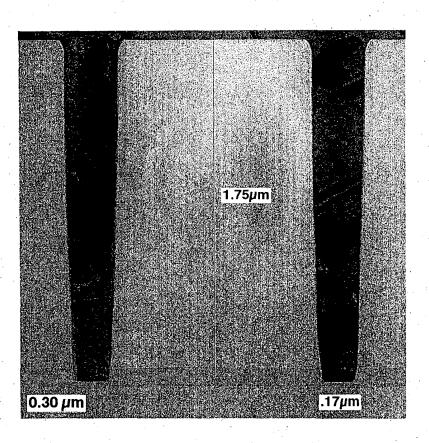


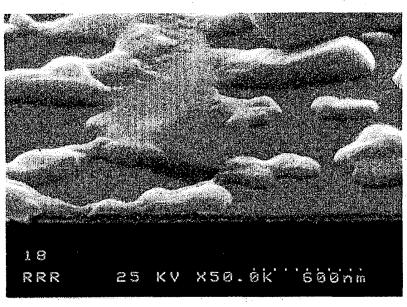
Fig. 6

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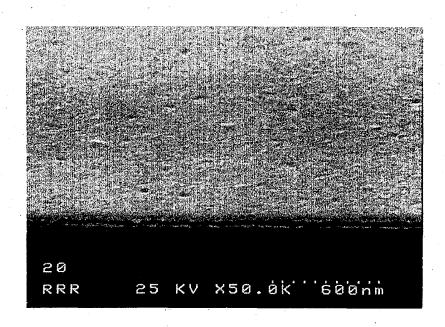
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1x50 TiN Plasma

Fig. 7A



1x50 TiSiN Plasma

Fig. 7B

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80 sccm SiH4, 300 sccm N2, 2.0 Torr

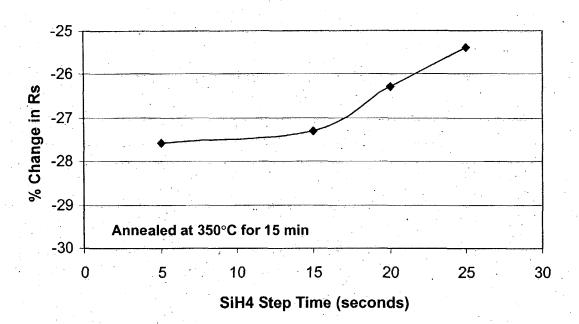


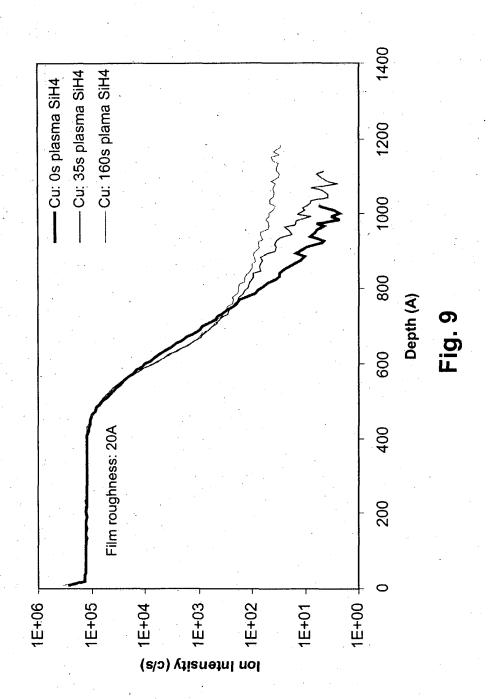
Fig. 8

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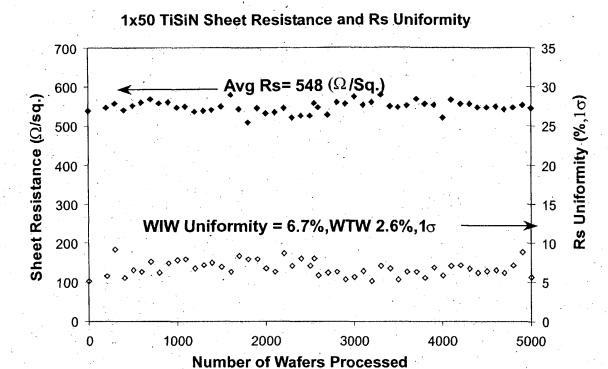


Fig. 10A

1X35 TiSiN Rs and Rs Uniformity

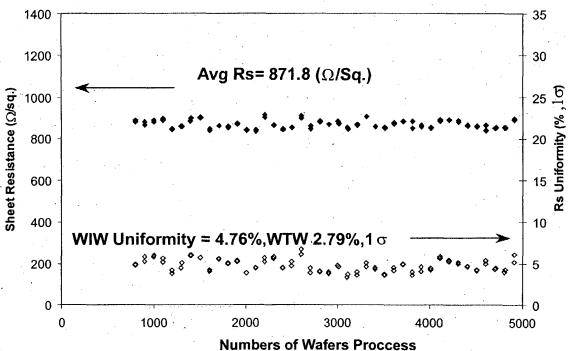


Fig. 10B

Atty Dkt. No.: U.S. Serial No.:

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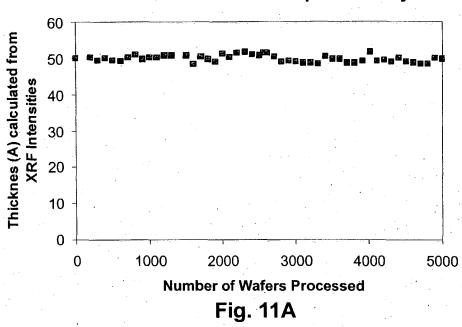
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1x50 TiSiN Thickness Reproducibility



1x35 TiSiN Thickness Reproducibility

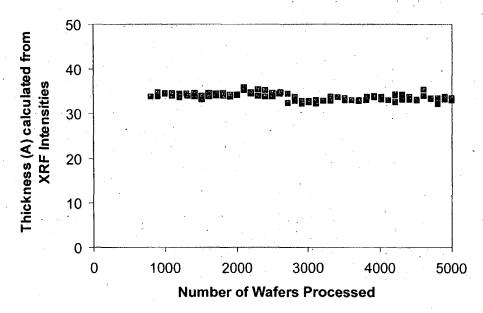
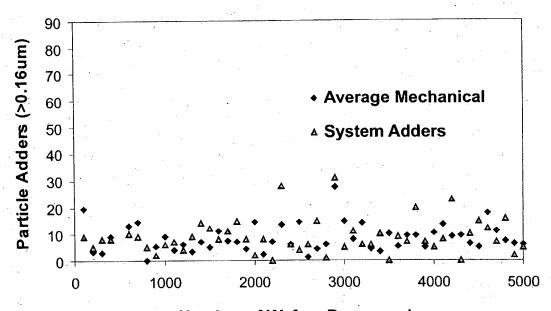


Fig. 11B

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Number of Wafers Processed Fig. 12A

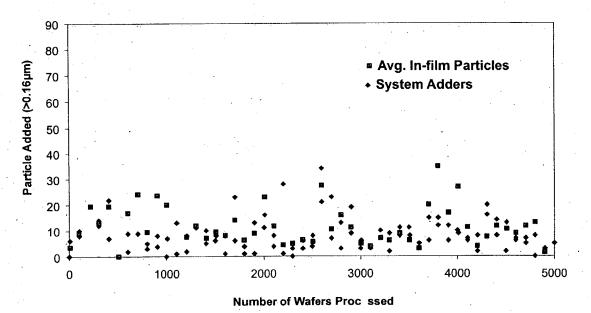


Fig. 12B

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1x50 TiSiN Rs and Rs Uniformity After 1 Hour Idle

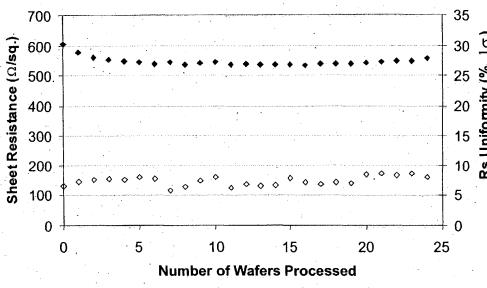


Fig. 13A

1X50 TiSiN Thickness from XRF Intensities After 1 Hour Idle

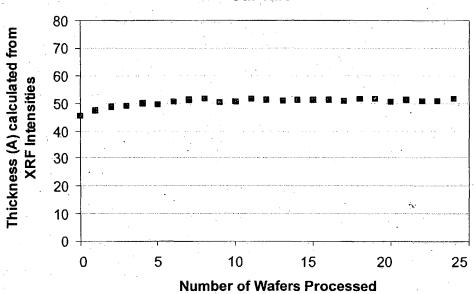


Fig. 13B